



## Surface Mount Glass Passivated Rectifier

Reverse Voltage 1000 Volts Forward Current 1.5 Amperes

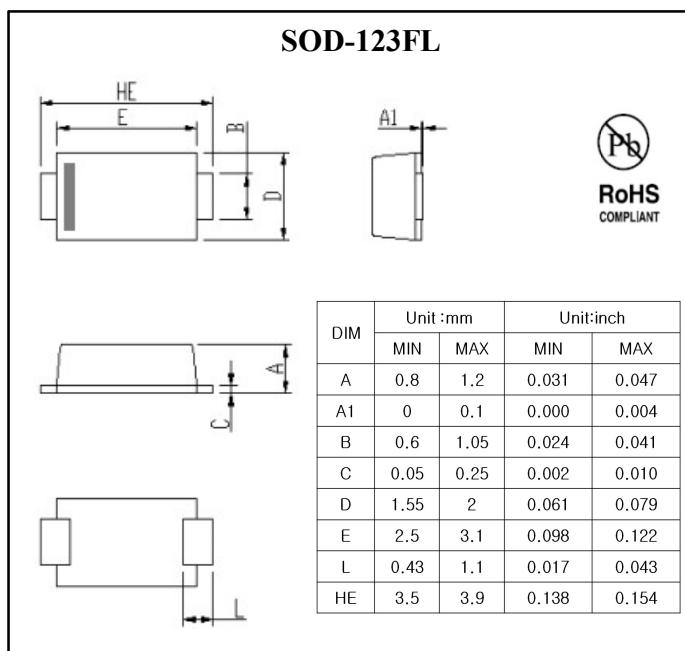
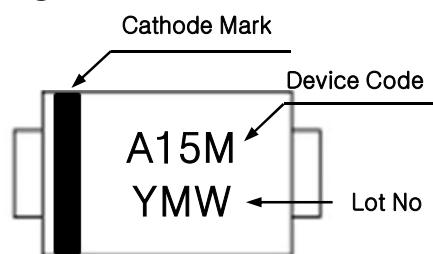
### Features

- Glass passivated chip junction
- For surface mounted application
- Low forward voltage drop
- Low profile package
- Built-in strain relief, ideal for automated placement
- High temperature soldering guaranteed : 260°C/10 seconds

### Mechanical Data

- Case : JEDEC SOD-123FL molded plastic over glass passivated chip
- Terminals : Solder plated, Solderable per MIL-STD-750, method 2026
- Polarity : Color band denotes cathode end
- Weight : 0.015gram

### Marking



### Maximum Ratings & Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified

Single phase half wave 60 Hz, resistive or inductive load

For capacitive load, derate current by 20%

Parameter	Symbol	Rated Value	Unit	Remark
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	1000	V	
Maximum RMS Voltage	V <sub>RMS</sub>	700	V	
Maximum DC Blocking Voltage	V <sub>DC</sub>	1000	V	
Maximum Average Forward Rectified Current at TL (See Fig. 1)	I <sub>F(AV)</sub>	1.5	A	
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load	I <sub>FSM</sub>	50	A	
Maximum instantaneous forward voltage at 1.5A	V <sub>F</sub>	1.1	V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	I <sub>R</sub>	5.0 125	uA	Ta=25°C Ta=125 °C
Typical Thermal Resistance	R <sub>th(j-a)</sub> R <sub>th(j-l)</sub>	53 16	°C/W	Note 1
Typical Junction Capacitance	C <sub>J</sub>	30	pF	Note 2
Operation Junction Temperature Range	T <sub>J</sub>	-55 to +150	°C	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C	

Note 1. Thermal resistance from junction to ambient and from junction to lead mounted on

Note 2. Measured at 1.0MHz and applied reverse voltage of 4.0 volts



Ratings and Characteristics Curves (Ta=25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

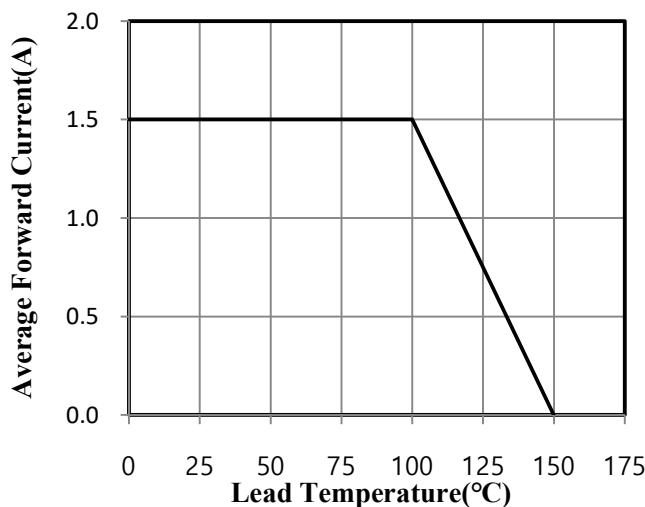


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

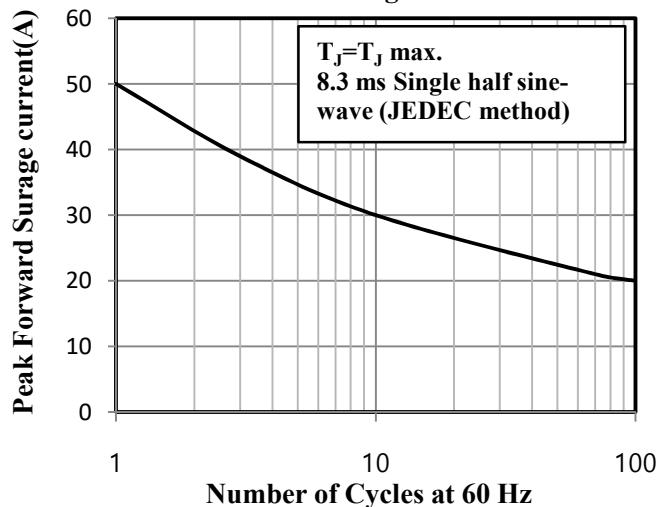


Fig.3 Typical Instantaneous Forward Characteristics

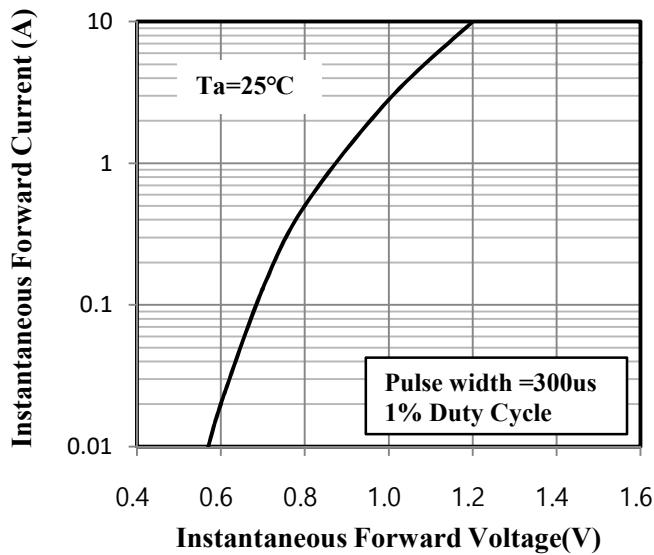


Fig.4 Typical Junction Capacitance

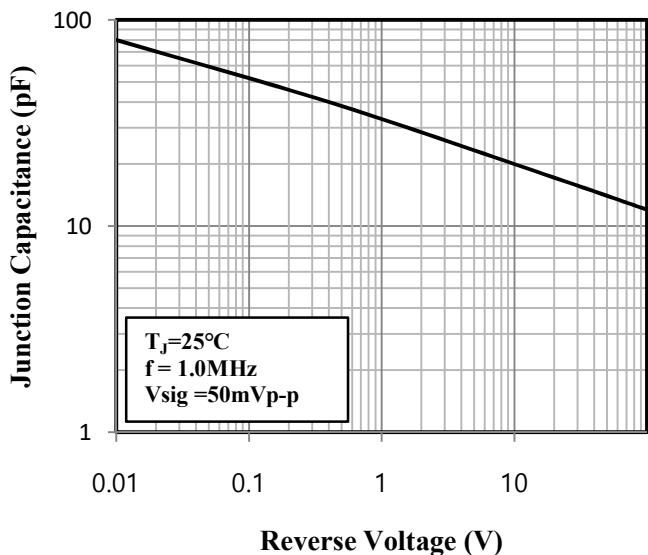


Fig.5 Typical Reverse Characteristics

